

**Alternate Assembly Site of Select Isolator Products in  
8L/16L SOIC\_N, 16L/20L SOIC\_W and 16L/20L SOIC\_IC at ASE Chungli**

**Automotive Qualification Results Summary  
of 16L SOIC\_W Package at ASE Chungli**

| <b>QUALIFICATION RESULT</b>            |                            |                    |               |
|--|----------------------------|--------------------|---------------|
| <b>TEST</b>                            | <b>SPECIFICATION</b>       | <b>SAMPLE SIZE</b> | <b>RESULT</b> |
| Temperature Cycle (TC)*                | JEDEC <i>JESD22-A104</i>   | 3 x 77             | PASS          |
| Highly Accelerated Stress Test (HAST)* | JEDEC <i>JESD22-A110</i>   | 3 x 77             | PASS          |
| Autoclave (AC)*                        | JEDEC <i>JESD22-A102</i>   | 3 x 77             | PASS          |
| Solder Heat Resistance (SHR)*          | JEDEC/IPC <i>J-STD-020</i> | 3 x 11             | PASS          |
| Solderability                          | JEDEC <i>JESD22-B102</i>   | 3 x 5              | PASS          |
| High Temperature Storage (HTS)         | JEDEC <i>JESD22-A103</i>   | 1 x 77             | PASS          |

\*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C. TC samples were subjected to wire-pull test after 500 cycles with results within specification limits

**Alternate Assembly Site of Select Isolator Products in  
8L/16L SOIC\_N, 16L/20L SOIC\_W and 16L/20L SOIC\_IC at ASE Chungli**

**Automotive Qualification Results Summary  
of 8L/16L SOIC\_N Package at ASE Chungli**

| <b>QUALIFICATION RESULT</b>            |                            |                    |               |
|--|----------------------------|--------------------|---------------|
| <b>TEST</b>                            | <b>SPECIFICATION</b>       | <b>SAMPLE SIZE</b> | <b>RESULT</b> |
| Temperature Cycle (TC)*                | JEDEC <i>JESD22-A104</i>   | 3 x 77             | PASS          |
| Highly Accelerated Stress Test (HAST)* | JEDEC <i>JESD22-A110</i>   | 3 x 77             | PASS          |
| Autoclave (AC)*                        | JEDEC <i>JESD22-A102</i>   | 3 x 77             | PASS          |
| Solder Heat Resistance (SHR)*          | JEDEC/IPC <i>J-STD-020</i> | 3 x 11             | PASS          |
| Solderability                          | JEDEC <i>JESD22-B102</i>   | 3 x 5              | PASS          |
| High Temperature Storage (HTS)         | JEDEC <i>JESD22-A103</i>   | 1 x 77             | PASS          |

\*These samples were subjected to preconditioning (per J-STD-020 Level 1) prior to the start of the stress test. Level 1 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 168 hrs @ 85°C, 85%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C. TC samples were subjected to wire-pull test after 500 cycles with results within specification limits

## Material Set Change:

| Package Material Set |               | Carsem                       | ASE Chungli                 |
|----------------------|---------------|------------------------------|-----------------------------|
| SOIC_N               | Die Attach    | Ablestik 84-1LMISR4          | Hitachi EN4900GC            |
| SOIC_W               | Mold Compound | Sumitomo 6600H or G600C      | Sumitomo G700LY             |
| SOIC_IC              | Wire          | 1.0mil and 1.3 mil Gold Wire | 1.0mil and 1.3mil Gold Wire |

| Package Material Set |               | Carsem                       | ASE Chungli                 |
|----------------------|---------------|------------------------------|-----------------------------|
| SOIC_N               | Die Attach    | Ablestik 84-3J               | Ablestik 2025D              |
| SOIC_W               | Mold Compound | Sumitomo 6600H or G600C      | Sumitomo G700LY             |
| SOIC_IC              | Wire          | 1.0mil and 1.3 mil Gold Wire | 1.0mil and 1.3mil Gold Wire |



## Analog Devices, Inc. PCN Material Report (Proprietary Information)

| Existing Material |                | Material Added |                 | Material Removed |                |
|-------------------|----------------|----------------|-----------------|------------------|----------------|
| GENERICNUMBER     | MATERIALNUMBER | GENERICNUMBER  | MATERIALNUMBER  | GENERICNUMBER    | MATERIALNUMBER |
|                   |                | AD7401A        | ADW70015Z-0RL   |                  |                |
|                   |                | ADUM4401       | ADW80035ARWZ    |                  |                |
|                   |                | ADUM4401       | ADW80035ARWZ-RL |                  |                |